



VT-447

UL Approval: E214381

Version : Rev. 6

Datasheet

Halogen Free & High Tg

VT-447 CCL/Laminate VT-447 PP/Prepreg

General Information

- **Halogen Free** & High Tg (175°C) FR-4
- Laser Fluorescing
- **CAF Resistance**
- Low CTE
- Excellent Thermal Reliability

Application

For Single Side\Double Side\ Multilayer PWB & Lead Free Assembly Applications;

Availability

VT-447 Laminates are available in thickness from .002" to .200" and with the copper foil from 1/4oz to 12oz; Ventec can supply either reverse treated (RT) or double side treated copper foil. For cores $\leq .005$ ", it is recommended to use the reverse treated copper due to the low profile. The peel strength for RT foil is $\approx 1-2$ lbs/in (0.35Kg/m) less than Standard foil.

VT-447PP pre-pregs are available in many E-Glass styles, such as 7628, 7629, 1506, 1500, 2113, 2313, 3313, 2116, 1080, 1086, 1078, 106 & 1067.

Storage Condition & Shelf Life

		Prepreg		Laminate
Storage	Temperature	Below 23°C(73°F)	Below 5°C(41°F)	Room
Condition	Relative Humidity	Below 55%RH	/	/
Shelf Time*		2 Months	4 Months	12 Months(airproof)

* The pre-preg exceeding shelf time should be retested.



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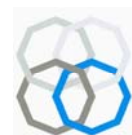
Properties Sheet: IPC-4101B Specification Sheet(s)/94

(Test Sample: .036"1/1)

Test Item		Test Condition	Unit	Specification	Test Result	
					VT-447	Normal FR4
Flexural Strength	Warp	As Recieved	MPa	>415	500	600
	Fill			>345	400	500
Peel Strength (for 1 oz)		As Recieved	Lb/in	6.0min	7.30	10~12
		After Heated			7.21	9~12
Glass Transition (Tg)	TMA	2.4.24	°C	—	173	125~135
	DSC	2.4.25	°C	—	180	136~140
	DMA	2.4.24C	°C	—	190	145~155
Decomposition Temp. (Td)		ASTM D3850	°C	—	370	290~310
Z-axis C.T.E Before Tg/After Tg		TMA	ppm/°C	60 /300	40 /220	50 /250
Moisture Absorption		D-24/23	%	0.35max	0.18	0.25
Volume Resistance	After Moisture	2.5.17.1	MΩ-cm	≥10 ⁶	5×10 ⁸	5×10 ⁸
	E-24/125			≥10 ³	5×10 ⁶	5×10 ⁶
Surface Resistance	After Moisture	2.5.17.1	MΩ	≥10 ⁴	5×10 ⁷	5×10 ⁷
	E-24/125			≥10 ³	5×10 ⁶	5×10 ⁶
Electric Strength		2.5.6.2	KV/mm	≥30	54	54
Dielectric Constant (Dk) *	250MHZ	2.5.5.3, 2.5.5.9, 2.5.5.5	—	5.4max	4.45	4.27
	1.0 GHz				4.40	4.26
	2.0 GHz				4.32	4.22
	10 GHz				4.25	4.08
Dispersion Factor (Df) *	250MHZ	2.5.5.3, 2.5.5.9, 2.5.5.5	—	0.035max	0.013	0.015
	1.0 GHz				0.014	0.015
	2.0 GHz				0.014	0.016
	10 GHz				0.016	0.018
Thermal Stress		Solder Dip @288°C	Sec	60 Sec	>300	90~120
Pressure Cook Test		15psi/30min /288 °C /10sec	Cycle	2 Cycles min.	10~12	6~8
Time to Delamination---T260		TMA	Minute	—	>60	20
Time to Delamination---T288		TMA	Minute	—	>30	3
Halogen Content		—	ppm	<900	<900	—
Flammability		UL94	—	V1	V0	V0
Comparative Tracking Index (CTI)		UL-7461 ASTM D3638	Volt	—	175~250 (Grade 3)	175~250 (Grade 3)
Chemical Resistance in 10% NaOH,60°C,30minutes		—	—	No measles	No	No

※ All test data provided are typical values and are not intended to be specification values.

※ ** Resin content of Dk & Df test sample 54%.



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Process Guideline

Press Condition

1. Heating rate(Rise of Rate) of material [Material Temperature]:
Programmable Press: 1.5-3.0°C/min (3~5°F/min) Manual Press:3~6°C/min (5~10°F/min)
2. Curing Temperature & Time: >60min at more than 185°C (356°F) [Material Temperature]
3. Full Pressure: ≥ 320 psi
4. Vacuuming should be continued until over 140°C (284°F) [Material Temperature]

Typical Drilling Parameters ($\varphi 0.3-1.0$ mm)

1. Spindle Speed:	120-180	KRPM
2. Feed Rate:	120-220	Inch / min
3. Retract Rate:	596-1000	Inch / min
4. Chip Load:	0.6~2.0	mil / Rev.

Desmearing Process

Desmear rate of **VT-447** is less than that of the conventional FR-4;
Minor adjustments to the desmear process may be necessary for the higher Tg materials;
Check with your chemical supplier for recommendations.